

## Electronic Patent Application Fee Transmittal

Application Number:	10563778			
Filing Date:	06-Jan-2006			
Title of Invention:	Hardenable pressure sensitive adhesive sheet for dicing/die-bonding and method for manufacturing semiconductor device			
First Named Inventor/Applicant Name:	Naoya Saiki			
Filer:	Kent E. Baldauf/Melissa Wyke			
Attorney Docket Number:	1217-053827			
Filed as Large Entity				
<b>U.S. National Stage under 35 USC 371 Filing Fees</b>				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
<b>Extension-of-Time:</b>				
Extension - 3 months with \$0 paid	1253	1	1110	1110

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>1110</b>